



PACKAGE MATERIAL DECLARATION DATASHEET

| | | | |
|--------------------------------|----------|--------------------------------|----------|
| Cypress Package Code | VZ | Body Size (mil/mm) | 300 mils |
| Package Weight – Site 1 | 1,210 mg | Package Weight – Site 2 | NA |

SUMMARY

The 32L-SOJ Pb-Free package is compliant to RoHS. Cypress Ordering Part Number containing an “X” (e.g. CY7C1328G-133AXI, CY2308SXC-1HT) meet the of Directive 2002/95/EC (RoHS) requirement.

ASSEMBLY Site 1 – Package Qualification Report # 040803 (Note 1)

I. DECLARATION OF PACKAGED UNITS

A. BANNED SUBSTANCES

Materials from Level A of the EIA/JIG/JGPSSI/EICTA Material Composition Declaration Guide and EU RoHS. listed in the table below are materials that are neither contained nor intentionally added to this product.

| Substances / Compounds | Weight by mg | PPM | Analysis Report (Note 2) |
|--|--------------|-------|-----------------------------|
| Cadmium and Cadmium Compounds | 0 | < 5.0 | CoA-VZ32-R |
| Hexavalent Chromium and its Compounds | 0 | <5.0 | |
| Lead and Lead Compounds | 0 | < 5.0 | |
| Mercury and Mercury Compounds | 0 | < 5.0 | |
| Polybrominated Biphenyls (PBB) | 0 | < 5.0 | |
| Polybrominated Diphenylethers (PBDE) | 0 | < 5.0 | |
| Asbestos | N/A | N/A | As per MSDS |
| Azo colorants | N/A | N/A | As per MSDS |
| Ozone Depleting Substances | N/A | N/A | As per MSDS |
| Polychlorinated Biphenyls (PCBs) | N/A | N/A | As per MSDS |
| Polychlorinated Napthalenes | N/A | N/A | As per MSDS |
| Radioactive Substances | N/A | N/A | As per MSDS |
| Shortchain Chlorinated Paraffins | N/A | N/A | As per MSDS |
| Tributyl Tin (TBT) and Triphenyl Tin (TPT) | N/A | N/A | As per MSDS |
| Tributyl Tin Oxide (TBTO) | N/A | N/A | As per MSDS |
| Formaldehyde | N/A | N/A | As per MSDS |

Note 1: Qualification reports are available at www.cypress.com. Access them by doing a Search on the Report #.

Note 2: Report available from Cypress Sales Offices or Distributors.

Note 3: Materials/substances not declared in Section I-A and I-B of this document are considered “non-existent in the product”. In order to report exactly 100% material composition, some numbers were rounded to the nearest 0.01 percent. Cypress Semiconductor material information are calculated using MSDS, Material Analysis Reports and Cypress Assembly sites information



B. MATERIAL COMPOSITION (Note 3)

| Material | Purpose of Use | Substance Composition | CAS Number | Weight by mg | PPM | % |
|---------------|------------------|--------------------------|------------|--------------|---------|--------|
| Leadframe | Base Material | Cu | 7440-50-8 | 232.84 | 192,434 | 19.24% |
| | | Fe | 7439-89-6 | 2.44 | 2,018 | 0.20% |
| | | P | 7723-14-0 | 1.59 | 1,312 | 0.13% |
| | | Zn | 7440-66-6 | 7.33 | 6,055 | 0.61% |
| Lead Finish | External Plating | Ni | 7440-02-0 | 0.19 | 250 | 0.01% |
| | | Pd | 7440-05-3 | 0.01 | 13 | 0.00% |
| | | Au | 7440-57-5 | 0.00 | 4 | 0.00% |
| Die Attach | Adhesive | Ag | 7440-22-4 | 0.24 | 196 | 0.02% |
| | | Proprietary bismaleimide | ----- | 0.02 | 20 | 0.00% |
| | | Proprietary polymer | ----- | 0.02 | 17 | 0.00% |
| | | Methacrylate | ----- | 0.01 | 5 | 0.00% |
| | | Acrylate ester | ----- | 0.01 | 5 | 0.00% |
| | | Organic peroxide | ----- | 0.01 | 5 | 0.00% |
| Die | Circuit | Si | 7440-21-3 | 0.96 | 3,801 | 0.08% |
| Wire | Interconnect | Au | 7440-57-5 | 4.60 | 790 | 0.38% |
| Mold Compound | Encapsulation | Solid Epoxy Resin | ----- | 76.76 | 63,451 | 6.34% |
| | | Phenol Resin | ----- | 76.76 | 63,451 | 6.34% |
| | | Antimony Trioxide | 1309-64-4 | 9.60 | 7,931 | 0.79% |
| | | Carbon Black | 1333-86-4 | 9.60 | 7,931 | 0.79% |
| | | Fused Silica | 60676-86-0 | 767.60 | 634,512 | 63.44% |
| | | Crystalline Silica | 14808-60-7 | 19.19 | 15,863 | 1.59% |

Package Weight (mg): **1,210** **% Total:** **100**

II. DECLARATION OF PACKAGING INDIRECT MATERIALS

| Type | Material | Cadmium PPM | Mercury PPM | Analysis Report (Note2) |
|-------------|--------------------------------|-------------|-------------|-------------------------|
| Tape & Reel | Cover tape | < 5.0 | < 5.0 | CoA-COVT-R |
| | Carrier tape | < 5.0 | < 5.0 | CoA-CART-R |
| | Plastic Reel | < 5.0 | < 5.0 | CoA-PLRL-R |
| Tray | | N/A | N/A | N/A |
| Tube | Plastic Tube | < 5.0 | < 5.0 | CoA-PLTB-R |
| | End Plug | < 5.0 | < 5.0 | CoA-EPLG-R |
| | End Pin | < 5.0 | TBD | CoA-EPIN-R |
| Others | Moisture Barrier bag | < 5.0 | < 5.0 | CoA-MBBG-R |
| | Shielding bag | < 5.0 | < 5.0 | CoA-SBAG-R |
| | Protective Band | < 5.0 | < 5.0 | CoA-PROB-R |
| | Shipping and inner / pizza box | < 5.0 | < 5.0 | CoA-ABOX-R |
| | Desiccant | < 5.0 | < 5.0 | CoA-DESS-R |
| | Bubble Pack | < 5.0 | < 5.0 | CoA-BUBP-R |

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Document History Page

Document Title: 32L-SOJ Pb-Free PMDD
Document Number: 001-03013

| Rev. | ECN No. | Orig. of Change | Description of Change |
|------|---------|-----------------|-----------------------|
| ** | 385301 | EML | New document |

Distribution: E-CML

Posting: None

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